

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application. Please cancel claims 68 and 91, amend claims 65, 69, 77-78, 90 and 92 as follows:

Listing of Claims:

1-64. (Canceled)

65. (Currently Amended) A system for manufacturing a planarizing slurry used in planarization of microelectronic-device substrate assemblies, comprising:

a first feed line for containing a flow of a first solution having a plurality of first abrasive particles of a first size, the first solution not having been previously used to planarize a microelectronic substrate;

a second feed line for containing a separate flow of a second solution having a plurality of second abrasive particles of a second size, the first abrasive particles size being different than the second abrasive particles size;

a first removal unit coupled to the first feed line to selectively remove a first type size of selected abrasive particles from the first abrasive particles; and

a second removal unit coupled to the second feed line to selectively remove a second size of selected abrasive particles from the second abrasive particles; and

a combination feed line operatively coupled to the first removal unit and the second feed line removal unit for containing a combined flow of the first and second solutions after removing the first and second types of selected abrasive particles from the first and second solutions.

66. (Original) The system of claim 65 wherein the first removal unit comprises a first filtration unit.

67. (Previously Presented) The system of claim 66 wherein the first filtration unit comprises a filter that removes abrasive particles having a particles size greater than approximately 0.3 μm .

68. (Canceled)

69. (Currently Amended) The system of claim ~~68~~⁶⁵ wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particles size greater than approximately 0.3 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particles size greater than approximately 0.050 μm .

70-74. (Canceled)

75. (Previously Presented) The system of claim 65 wherein the first removal unit comprises a first filtration unit that removes abrasive particles having a particle size greater than approximately 0.8 μm .

76. (Previously Presented) The system of claim 65 wherein the first removal unit comprises a first filtration unit that removes abrasive particles having a particle size greater than approximately 1.0 μm .

77. (Currently Amended) The system of claim ~~68~~⁶⁵ wherein the second removal unit comprises a first filtration unit that removes abrasive particles having a particle size greater than approximately 0.15 μm .

78. (Currently Amended) The system of claim 68_65 wherein the second removal unit comprises a first filtration unit that removes abrasive particles having a particle size greater than approximately 0.05 μm .

79. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 1.0 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.05 μm .

80. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 1.0 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.15 μm .

81. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.8 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.05 μm .

82. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.8 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.15 μm .

83. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a

particle size greater than approximately 0.3 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having particle size greater than approximately 0.05 μm .

84. (Previously Presented) The system of claim 69 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.3 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having particle size greater than approximately 0.15 μm .

85. (Previously Presented) The system of claim 65 further comprising a mixing unit configured to mix the combined flow of the first and second solutions.

86. (Previously Presented) The system of claim 65 further comprising a conduit through which the combined flow of the first and second solutions is passed to provide a turbulent zone for mixing the combined flow.

87. (Previously Presented) The system of claim 65 further comprising a volume control unit configured to mix 1-99% by volume of the first filtered solution with 1-99% by volume of the second solution.

88. (Previously Presented) The system of claim 87 wherein the volume control unit is configured to alter a mix ratio of the first filtered solution and the second solution during a single polishing cycle.

89. (Previously Presented) The system of claim 88 wherein the volume control unit is configured to change from a first mix ratio of the first filtered solution and the second solution to a second mix ratio of the first filtered solution and the second solution.

90. (Currently Amended) A system for manufacturing a planarizing slurry used

in planarization of microelectronic-device substrate assemblies, comprising:

a first feed line for containing a flow of a first solution having a plurality of first abrasive particles of a first size, the first solution not having been previously used to planarize a microelectronic substrate;

a second feed line for containing a separate flow of a second solution having a plurality of second abrasive particles of a second size, the first abrasive particles size being different than the second abrasive particles size;

a first filtration unit coupled to the first feed line to selectively remove a first type size of selected abrasive particles from the first abrasive particles; and

a second removal unit coupled to the second feed line to selectively remove a second size of selected abrasive particles from the second abrasive particles;

a combination feed line operatively coupled to the first removal unit and the second feed line removal unit for containing a combined flow of the first and second solutions after removing the first and second types of selected abrasive particles from the first and second solutions;

at least one of a mixer configured to mix the combined flow and a conduit through which the combined flow is passed to form a turbulent zone; and

a slurry dispenser coupled to the combination feed line to dispense the abrasive slurry from the combination line.

91. (Canceled)

92. (Currently Amended) The system of claim 91 90 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.3 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having particle size greater than approximately 0.05 μm .

93. (Previously Presented) The system of claim 92 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 1.0 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.05 μm .

94. (Previously Presented) The system of claim 92 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 1.0 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.15 μm .

95. (Previously Presented) The system of claim 92 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.8 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.05 μm .

96. (Previously Presented) The system of claim 92 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.8 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.15 μm .

97. (Previously Presented) The system of claim 92 wherein:

the first filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.3 μm ; and

the second filtration unit comprises a filter that removes abrasive particles having a particle size greater than approximately 0.15 μm .

98. (Previously Presented) The system of claim 90 further comprising a volume control unit configured to mix 1-99% by volume of the first filtered solution with 1-99% by volume of the second solution.

99. (Previously Presented) The system of claim 98 wherein the volume control unit is configured to alter a mix ratio of the first filtered solution and the second solution during a single polishing cycle.

100. (Previously Presented) The system of claim 99 wherein the volume control unit is configured to change from a first mix ratio of the first filtered solution and the second solution to a second mix ratio of the first filtered solution and the second solution.